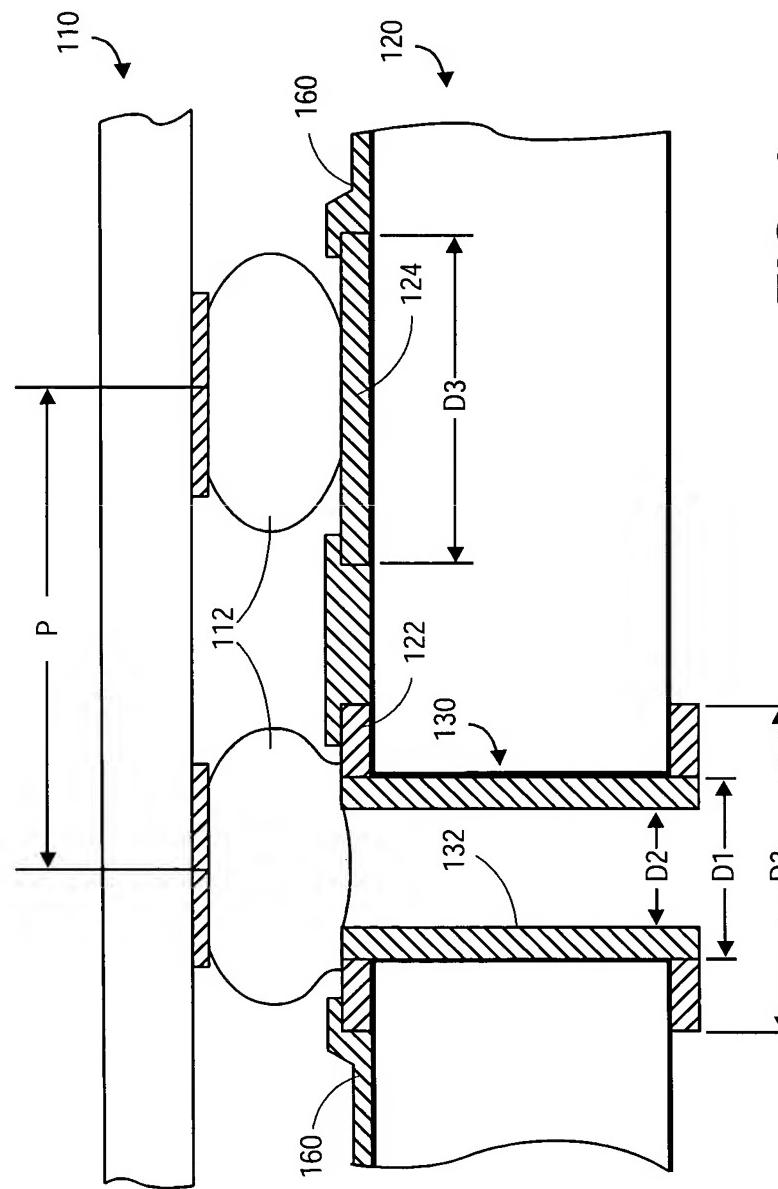


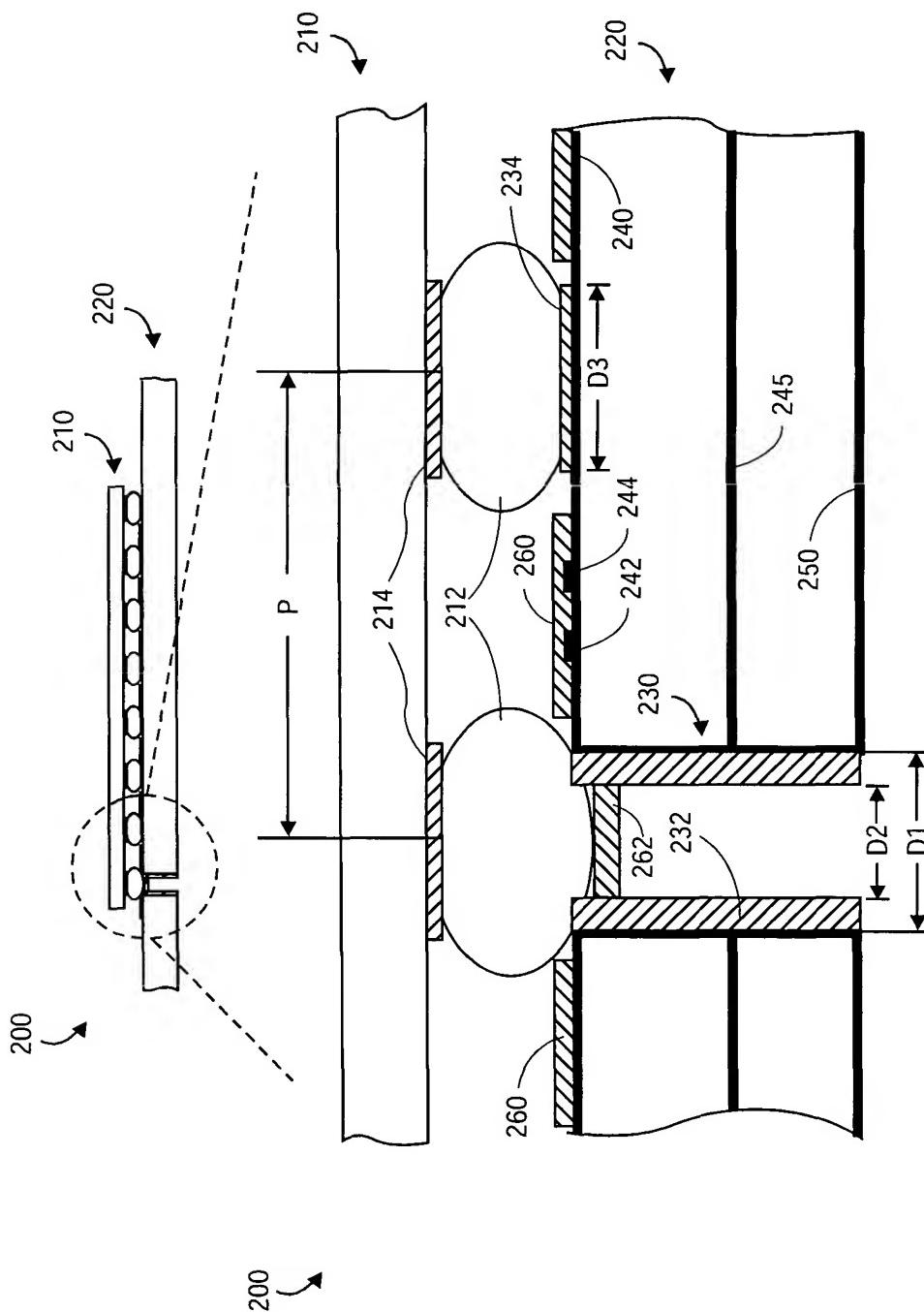
42390P13858  
APPARATUS AND METHOD FOR INTERCONNECTION BETWEEN A COMPONENT AND A  
PRINTED CIRCUIT BOARD  
Terrance J. Dishongh, et al.



**FIG. 1**  
(PRIOR ART)

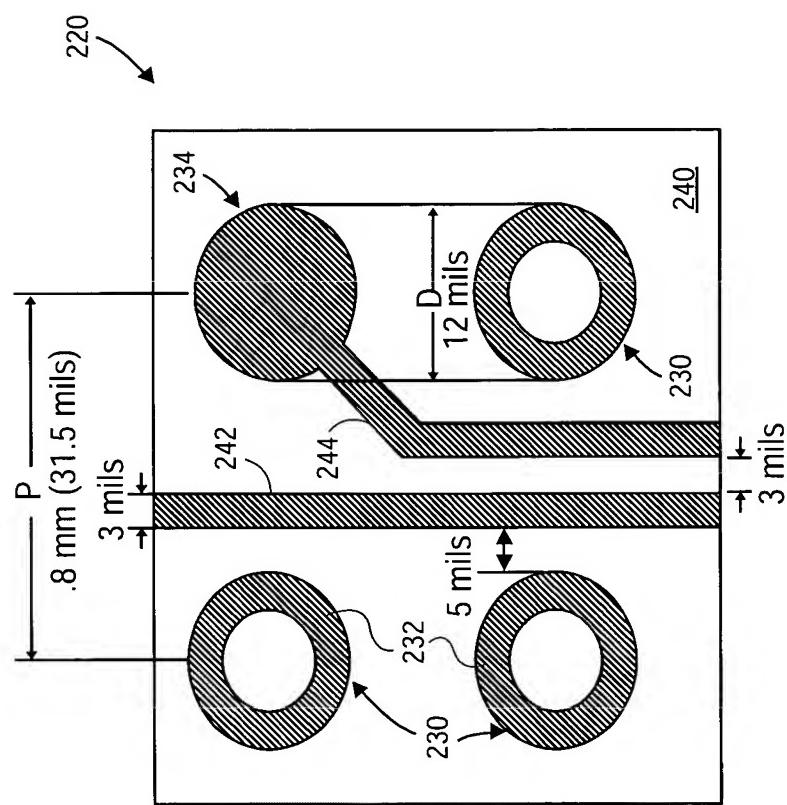
42390P13858  
APPARATUS AND METHOD FOR INTERCONNECTION BETWEEN A COMPONENT AND A  
PRINTED CIRCUIT BOARD  
Terrance J. Dishongh, et al.

FIG. 2



42390P13858  
APPARATUS AND METHOD FOR INTERCONNECTION BETWEEN A COMPONENT AND A  
PRINTED CIRCUIT BOARD  
Terrance J. Dishongh, et al.

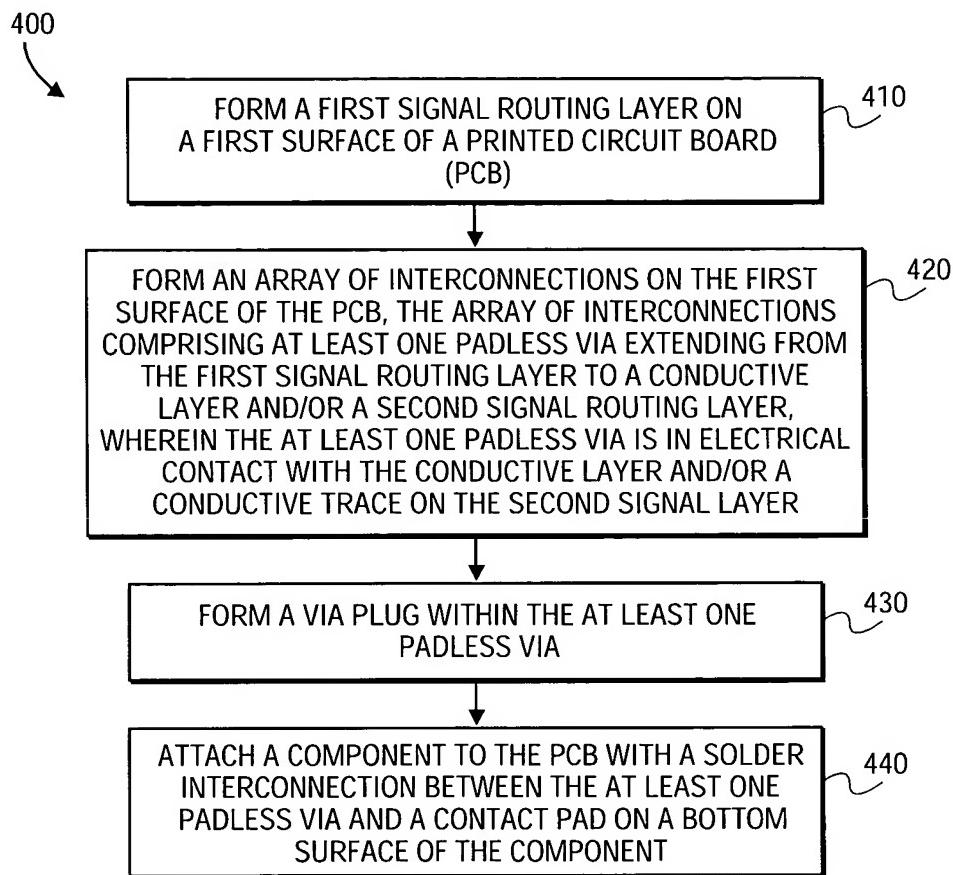
3/8



**FIG. 3**

42390P13858  
APPARATUS AND METHOD FOR INTERCONNECTION BETWEEN A COMPONENT AND A  
PRINTED CIRCUIT BOARD  
Terrance J. Dishongh, et al.

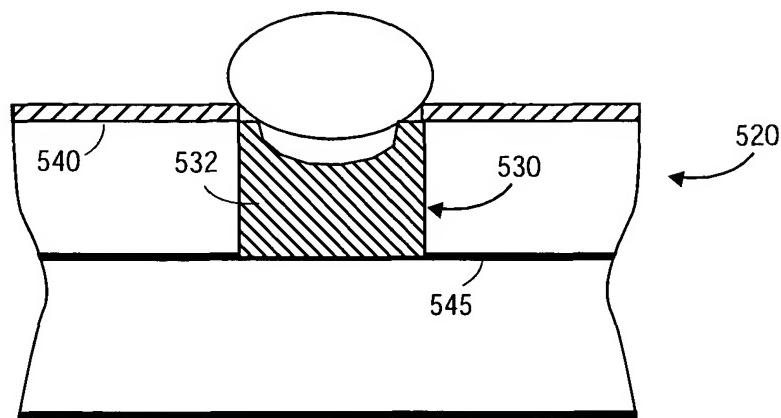
4/8



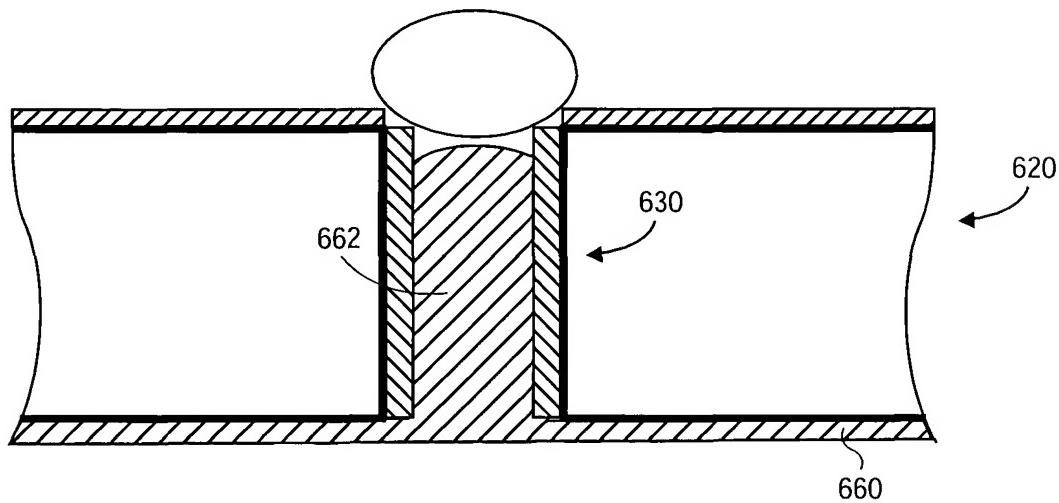
**FIG. 4**

42390P13858  
APPARATUS AND METHOD FOR INTERCONNECTION BETWEEN A COMPONENT AND A  
PRINTED CIRCUIT BOARD  
Terrance J. Dishongh, et al.

5/8



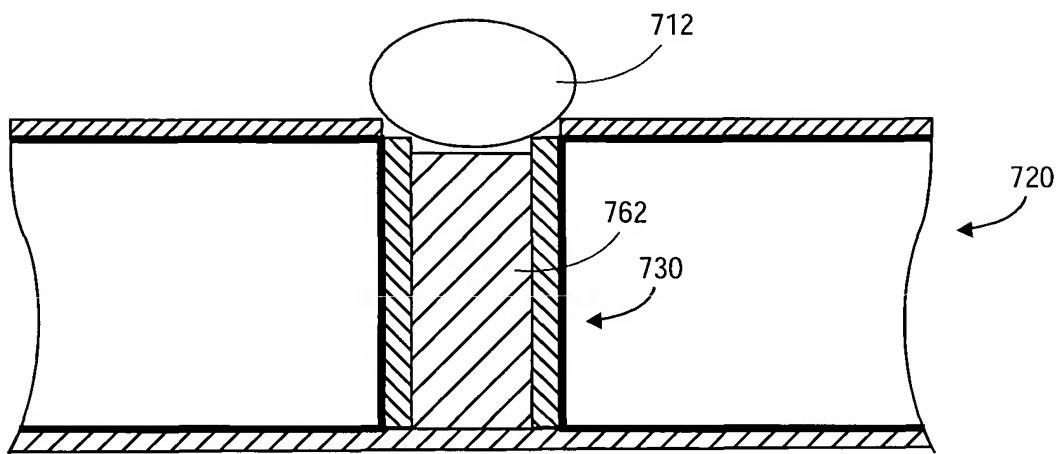
**FIG. 5**



**FIG. 6**

42390P13858  
APPARATUS AND METHOD FOR INTERCONNECTION BETWEEN A COMPONENT AND A  
PRINTED CIRCUIT BOARD  
Terrance J. Dishongh, et al.

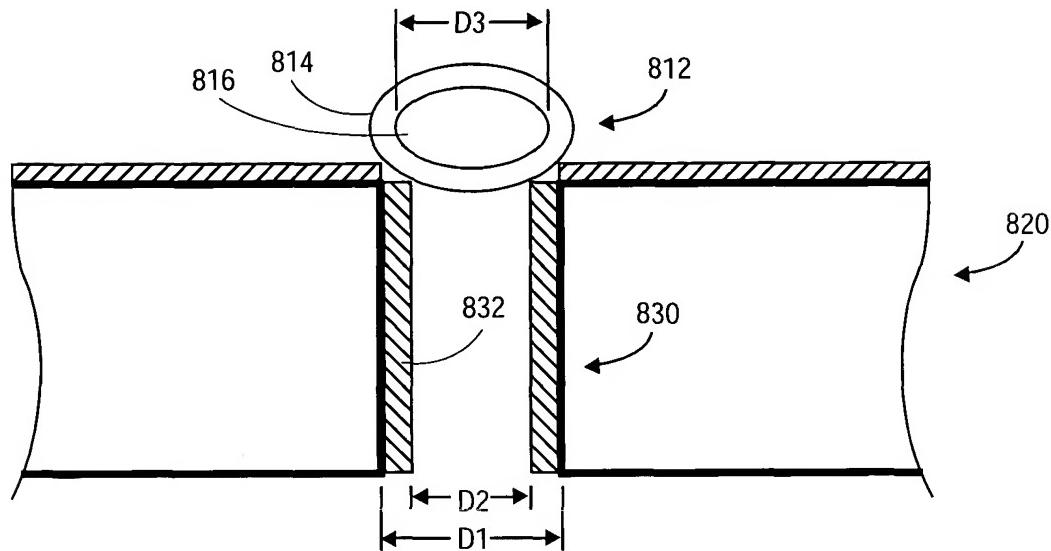
6/8



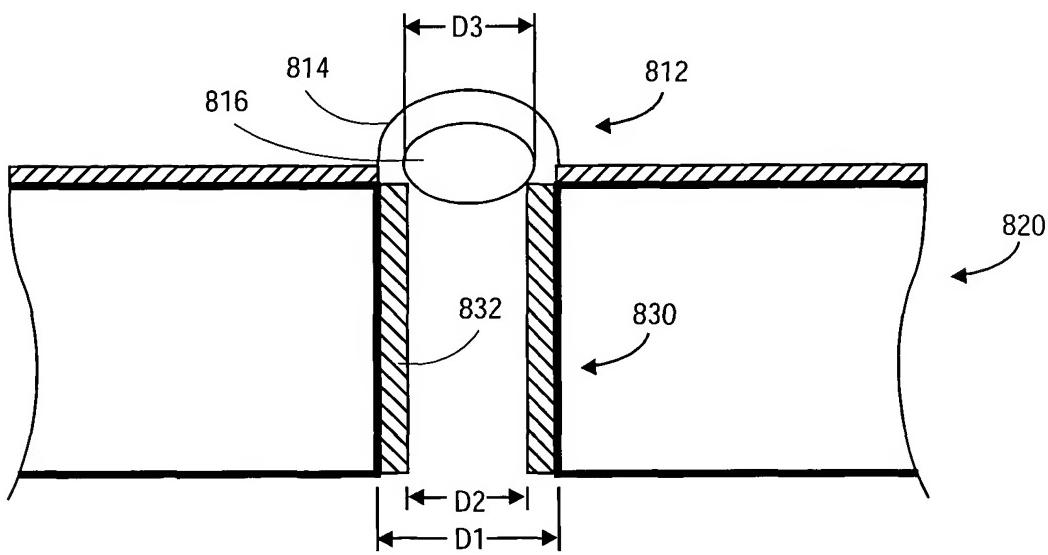
**FIG. 7**

42390P13858  
APPARATUS AND METHOD FOR INTERCONNECTION BETWEEN A COMPONENT AND A  
PRINTED CIRCUIT BOARD  
Terrance J. Dishongh, et al.

7/8



**FIG. 8A**



**FIG. 8B**

Routable Traces Between Interconnections Trace/Space = 3/3 mils, Trace-Via spacing = 5 mils		Component Pitch (mm)			
Type	Diameter (mils)	0.5	0.75	0.8	1
Padless via	6	1	2	3	4
Padless via	8	0	2	2	4
Padless via	12	0	1	2	3
Padless via	18	X	0	1	2
Contact Pad	24	X	X	0	1
Contact Pad	32	X	X	X	0
X = Overlap					

**FIG. 9**